EE5807 Special Topics Course Syllabus: Millimeter-Wave & Terahertz CMOS

SABANCI ÜNİVERSİTESİ

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Office Hours



Online – any time our schedule match for short meetings
Office: FENS1064

Grading Policy

- Final 20%
- Midterm Project 25%
 - Deadline near the end of April
- Final Project 35%
- Final Presentation 20%



Lectures & Discussions



Lectures:

- Wednesdays 14:40-17:30 FENS L061
- **Discussion/Optional Sessions:**
- Fridays 12:40-14:30 FENS L061

General Outline



- 1. Fundamentals of Wireless Communications & Link Budget Calculations
- 2. Millimeter-Wave & Terahertz Transceivers
 - 1. Ultra-broadband high speed wireless communications
 - 2. Phased-arrays for wireless communications
- 3. Active & Passive Devices for millimeter-wave and terahertz circuit design
- 4. Design of millimeter-wave and terahertz circuits

1. Fundamentals of Wireless Communications &

- Link Budget Calculations
- Free space path loss
- Atmospheric radio-frequency windows
- Friis Transmission Equation
- Antenna & Distance Considerations
- Shannon's Channel Capacity
 - Maximum data-rate calculations
 - Incorporating with Friis Transmission Equation
 - Modulations and SNR requirements
 - Shannon's Channel Capacity for MIMO (optional at the moment)
- Signal to Noise and Distortion Ratio
 - Distortion due to non-linearity
 - 1dB gain compression, IM3 and IIP3
 - SNDR Calculation



2. Millimeter-Wave & Terahertz Transceivers

- Ultra-broadband high speed wireless communications
 - 60-GHz Transceiver example and considerations
 - D-Band Transceiver example and considerations
 - Sub-Terahertz 300-GHz Transceivers and considerations
- Phased-arrays for wireless communications
 - Phased-arrays for 5G base stations
- This part includes considerations such as the noise figure concept, linearity, output-backoff, ACLR and etc.

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3. Active and Passive Devices for mm-Wave and THz Circuits and Systems



- Process Design Kit, Importance of Device Modeling, Scattering Parameters
- De-embedding, T-Parameters, Pad Modeling
- Other Passive Components used in mm-Wave and THz circuits
- Transistor Modeling, Some amplifier examples and Revised L-2L De-embedding
- Differential De-embedding and Device Characterizations, mixedmode S-parameters
- Multi-port device characterizations based on two-port Network
 Analyzer Measurements

4. Design of mm-Wave and THz circuits



- (Quarter-Wavelength based SPDT switches, theoretical approach and design) PA+LNA SPDT-less antenna switching amplifier design
- Distributed common-source amplifier for ultra-wideband amplification
 - Staggered amplifier design
- Differential millimeter-wave amplifiers with distributed components
- Positive-feedback amplifiers for terahertz region
- Frequency multipliers for millimeter-wave and terahertz
- Millimeter-wave and THz Mixers